

ABSTRACT

A dicing die attach film containing a dicing film and a die attach film stacked on the dicing film, wherein the die attach film contains an organic solvent having a boiling point of 100°C or more and less than 150°C and a vapor pressure of 50 mmHg or less, and wherein an amount of the organic solvent in the die attach film satisfies the following (a):

- (a) when 1.0 g of the die attach film is immersed in 10.0 mL of acetone at 4°C for 24 hours, an amount of the organic solvent extracted into the acetone is 800 µg or less.

(No Suitable Figure)